



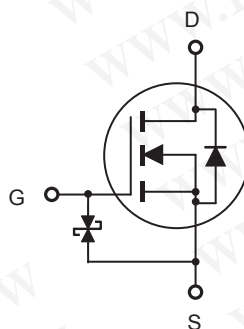
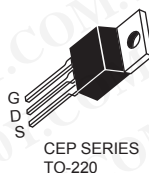
CEP83A3/CEB83A3

N-Channel Enhancement Mode Field Effect Transistor

FEATURES

- 30V, 100A, $R_{DS(ON)} = 5.3m\Omega$ @ $V_{GS} = 10V$.
 $R_{DS(ON)} = 8.0m\Omega$ @ $V_{GS} = 4.5V$.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handling capability.
- Lead free product is acquired.
- TO-220 & TO-263 package.

勝特力材料 886-3-5753170
 勝特力电子(上海) 86-21-34970699
 勝特力电子(深圳) 86-755-83298787
[Http://www.100y.com.tw](http://www.100y.com.tw)



ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	100	A
Drain Current-Pulsed ^a	I_{DM}	400	A
Maximum Power Dissipation @ $T_C = 25^\circ C$ - Derate above $25^\circ C$	P_D	100	W
		0.67	W/ $^\circ C$
Operating and Store Temperature Range	T_J, T_{stg}	-55 to 175	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.5	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	$^\circ C/W$



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Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

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Parameter	Symbol	Test Condition	Min	Typ	Max	Units	
Off Characteristics							
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	30			V	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30V, V_{GS} = 0V$			1	μA	
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{GS} = 20V, V_{DS} = 0V$			10	μA	
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{GS} = -20V, V_{DS} = 0V$			-10	μA	
On Characteristics^b							
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	1		3	V	
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 50A$		4.2	5.3	$m\Omega$	
		$V_{GS} = 4.5V, I_D = 40A$		6.0	8.0	$m\Omega$	
Dynamic Characteristics^c							
Forward Transconductance	g_{FS}	$V_{DS} = 10V, I_D = 15A$		27		S	
Input Capacitance	C_{iss}	$V_{DS} = 15V, V_{GS} = 0V, f = 1.0\text{ MHz}$		6350		μF	
Output Capacitance	C_{oss}				980		μF
Reverse Transfer Capacitance	C_{rss}				600		μF
Switching Characteristics^c							
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 15V, I_D = 1A, \square$ $V_{GS} = 10V, R_{GEN} = 6\Omega$		24		ns	
Turn-On Rise Time	t_r			22		ns	
Turn-Off Delay Time	$t_{d(off)}$			209		ns	
Turn-Off Fall Time	t_f			173		ns	
Total Gate Charge	Q_g	$V_{DS} = 15V, I_D = 16A, V_{GS} = 5V$		53		nC	
Gate-Source Charge	Q_{gs}			15		nC	
Gate-Drain Charge	Q_{gd}			22		nC	
Drain-Source Diode Characteristics and Maximum Ratings							
Drain-Source Diode Forward Current	I_S				100	A	
Drain-Source Diode Forward Voltage ^b	V_{SD}	$V_{GS} = 0V, I_S = 20A$			1.5	V	
Notes : □ a. Repetitive Rating : Pulse width limited by maximum junction temperature b. Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$. □ c. Guaranteed by design, not subject to production testing.							



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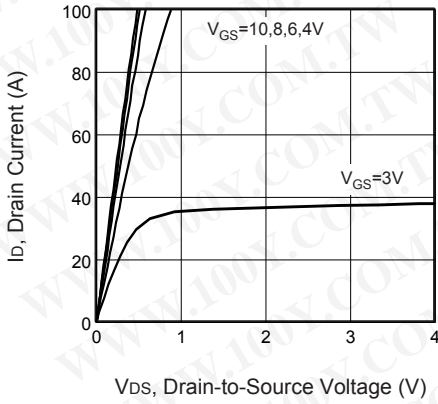


Figure 1. Output Characteristics

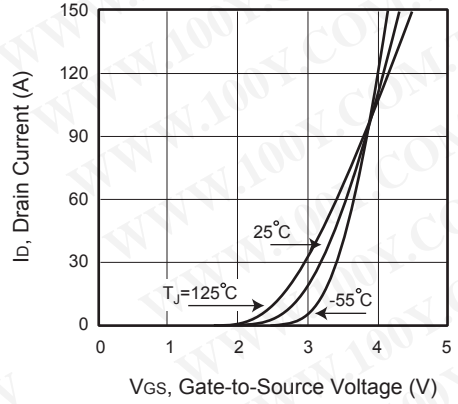


Figure 2. Transfer Characteristics

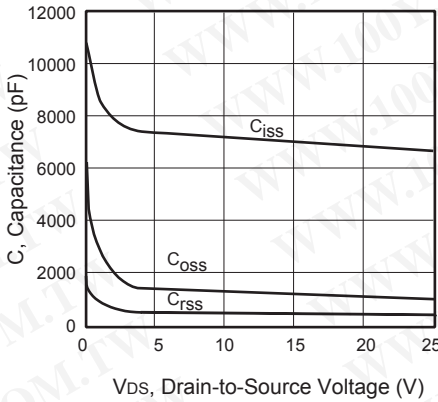


Figure 3. Capacitance

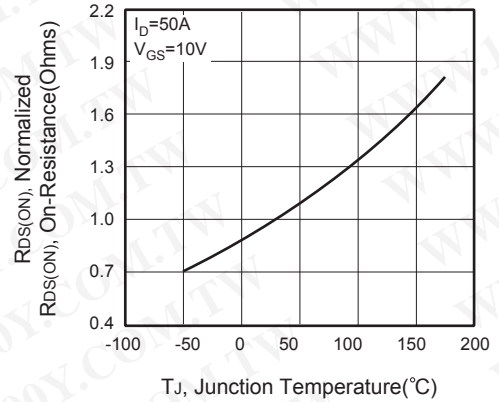


Figure 4. On-Resistance Variation with Temperature

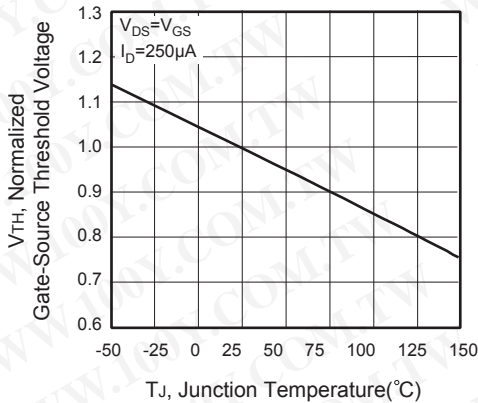


Figure 5. Gate Threshold Variation with Temperature

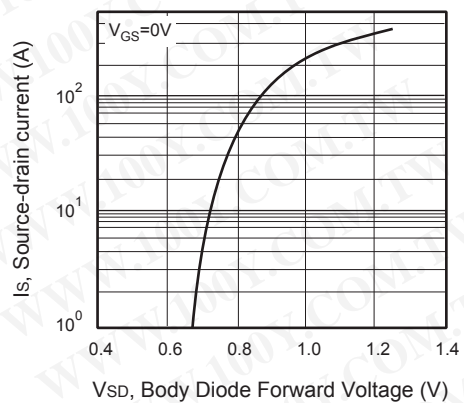


Figure 6. Body Diode Forward Voltage Variation with Source Current



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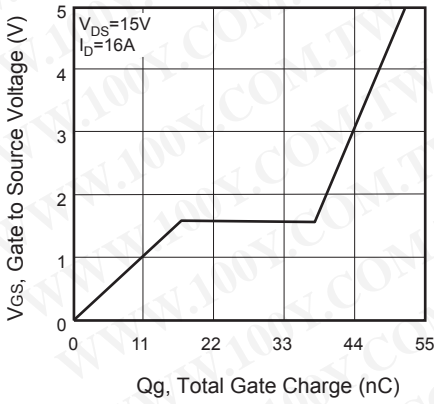


Figure 7. Gate Charge

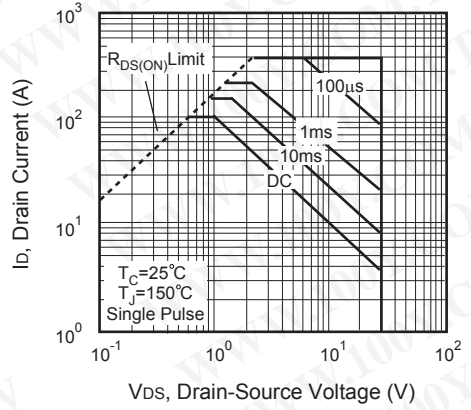


Figure 8. Maximum Safe Operating Area

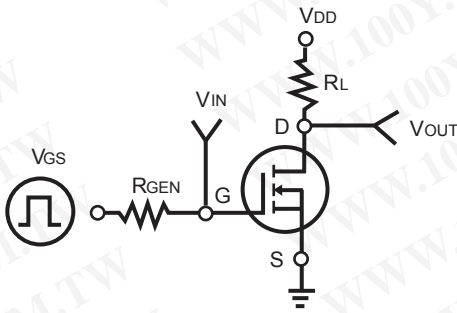


Figure 9. Switching Test Circuit

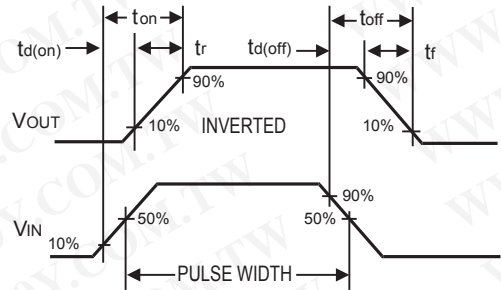


Figure 10. Switching Waveforms

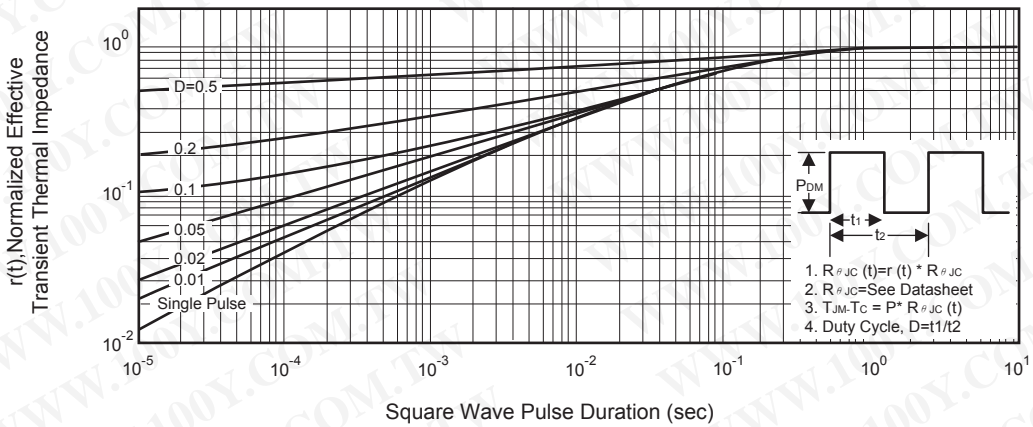


Figure 11. Normalized Thermal Transient Impedance Curve